

SOT1643-1

FBGA624; plastic, fine-pitch ball grid array; 624 bumps; 0.8 mm pitch; 21 mm x 21 mm x 2 mm body

8 February 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA624
Package type industry code	FBGA624
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-01-2016
Manufacturer package code	98ASA00330D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	2	2.16	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	624	-	



FBGA624; plastic, fine-pitch ball grid array; 624 bumps; 0.8 mm pitch; 21 mm x 21 mm x 2 mm body

2 Package outline

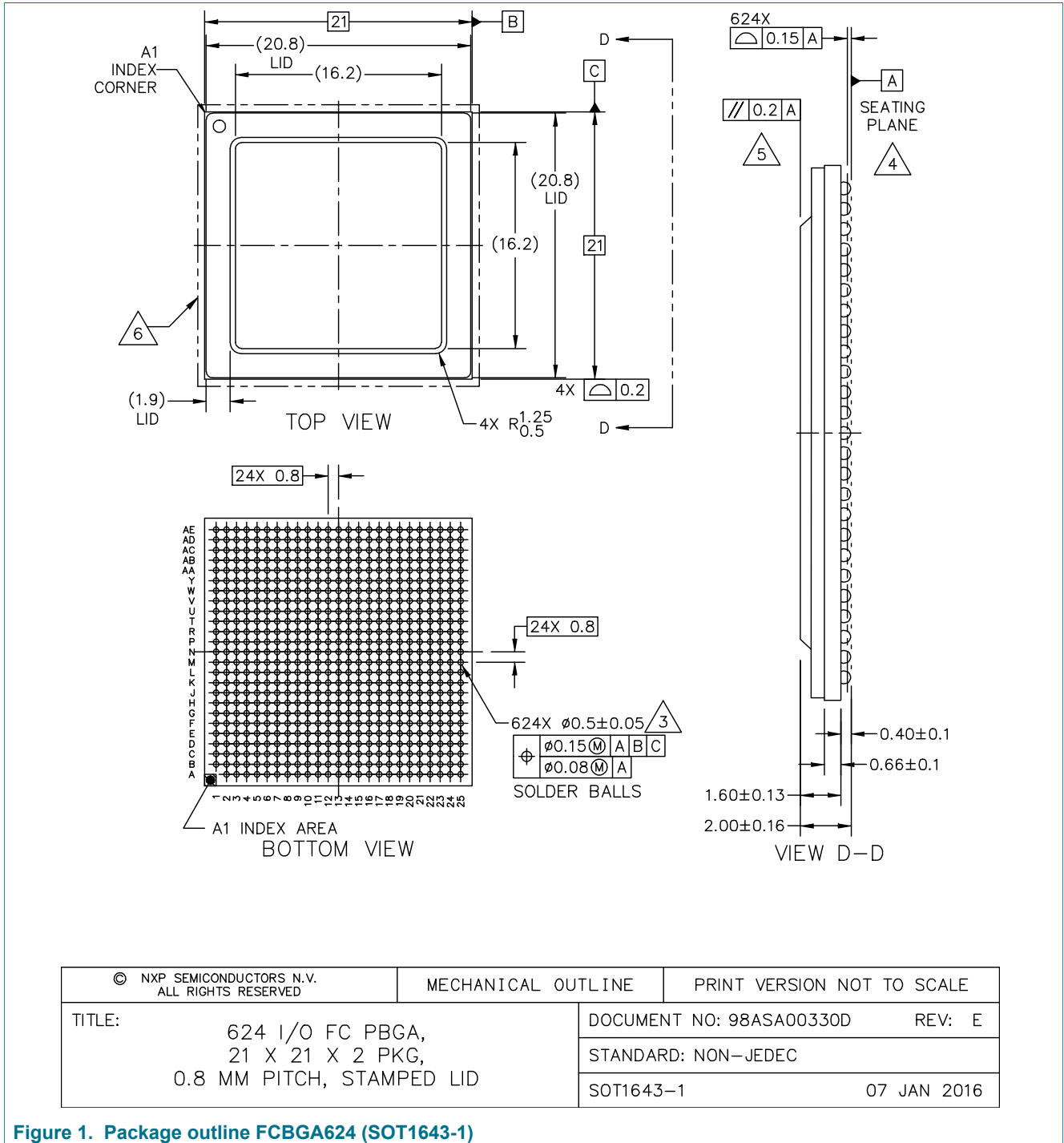


Figure 1. Package outline FCBGA624 (SOT1643-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. 21.2MM MAXIMUM PACKAGE ASSEMBLY (LID + LAMINATE) X AND Y.

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TITLE: 624 I/O FC PBGA, 21 X 21 X 2 PKG, 0.8 MM PITCH, STAMPED LID	DOCUMENT NO: 98ASA00330D	REV: E	
	STANDARD: NON-JEDEC		
	SOT1643-1	07 JAN 2016	

Figure 2. Package outline note FCBGA624 (SOT1643-1)

3 Legal information

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